

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	MMBTA05	MMBTA06	Unit
Collector-Base Voltage	V _{CBO}	60	80	V
Collector-Emitter Voltage	V _{CEO}	60	80	V
Emitter-Base Voltage	V_{EBO}	4.0		V
Collector Current	I _C	500		mA
Peak Collector Current	I _{CM}	1		A

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Note 6)	D-	310	mW	
Power Dissipation	(Note 7)	P_{D}	350] """	
Thermal Desistance, Junction to Ambient	(Note 6)	0	403	0C/M	
Thermal Resistance, Junction to Ambient	(Note 7)	$R_{\theta JA}$	357	°C/W	
Thermal Resistance, Junction to Leads	(Note 8)	$R_{ heta JL}$	350	°C/W	
Operating and Storage Temperature Range		$T_{J,}T_{STG}$	-55 to +150	°C	

ESD Ratings (Note 9)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes:

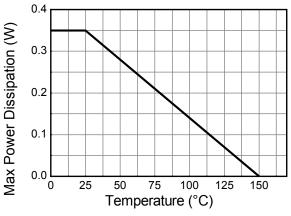
^{6.} For a device mounted on minimum recommended pad layout 1oz copper that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.

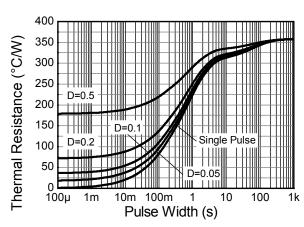
^{7.} Same as note (6), except the device is mounted on 15 mm x 15mm 1oz copper.

^{8.} Thermal resistance from junction to solder-point (at the end of the leads).
9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



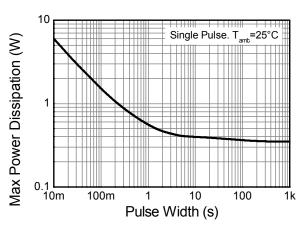
Thermal Characteristics and Derating Information





Derating Curve

Transient Thermal Impedance



Pulse Power Dissipation



Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	MMBTA05 MMBTA06	BV_CBO	60 80	_	V	I _C = 100μA, I _E = 0
Collector-Emitter Breakdown Voltage (Note 10)	MMBTA05 MMBTA06	BV _{CEO}	60 80	_	V	I _C = 10.0mA, I _B = 0
Emitter-Base Breakdown Voltage		BV _{EBO}	4.0	_	V	$I_E = 100 \mu A, I_C = 0$
Collector Cutoff Current	MMBTA05 MMBTA06	I _{CBO}		100	nA	$V_{CB} = 60V, I_{E} = 0$ $V_{CB} = 80V, I_{E} = 0$
Collector Cutoff Current	MMBTA05 MMBTA06	I _{CES}		100	nA	$V_{CE} = 60V, I_{BO} = 0V$ $V_{CE} = 80V, I_{BO} = 0V$
ON CHARACTERISTICS (Note 10)						
DC Current Gain		h _{FE}	100	_	_	$I_C = 10$ mA, $V_{CE} = 1.0$ V $I_C = 100$ mA, $V_{CE} = 1.0$ V
Collector-Emitter Saturation Voltage		V _{CE(sat)}	_	0.25	V	I _C = 100mA, I _B = 10mA
Base-Emitter Saturation Voltage		V _{BE(sat)}		1.2	V	I _C = 100mA, V _{CE} = 1.0V
SMALL SIGNAL CHARACTERISTICS						
Current Gain-Bandwidth Product		f _T	100	_	MHz	$V_{CE} = 2.0V$, $I_{C} = 10mA$, $f = 100MHz$

Note: 10. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.



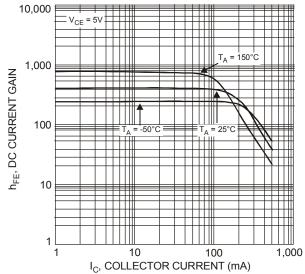
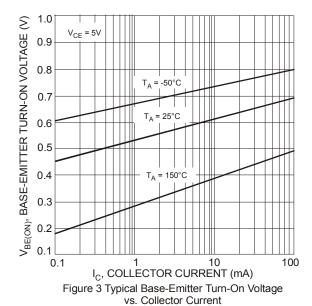


Figure 1 Typical DC Current Gain vs. Collector Current



10
V_{CB} = 80V

10
V_{CB} = 80V

10
0.01
25
50
75
100
125
T_A, AMBIENT TEMPERATURE (°C)
Figure 5 Typical Collector-Cutoff Current vs. Ambient Temperature

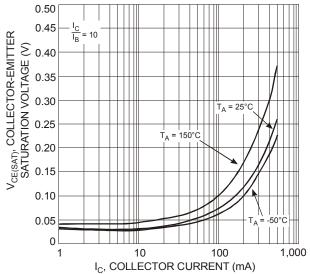


Figure 2 Collector-Emitter Saturation Voltage vs. Collector Current

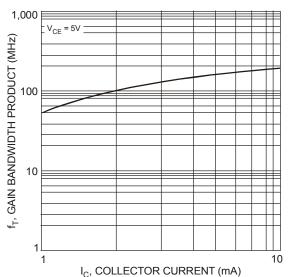


Figure 4 Typical Gain Bandwidth Product vs. Collector Current

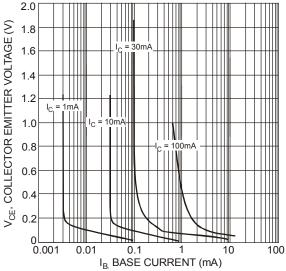
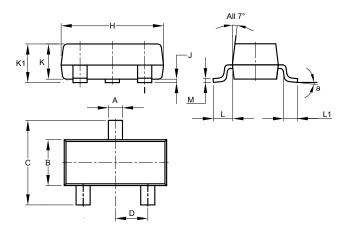


Figure 6 Typical Collector Saturation Region



Package Outline Dimensions

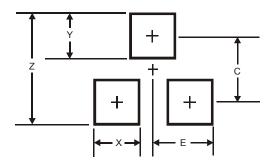
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23					
Dim	Min	Max	Тур		
Α	0.37	0.51	0.40		
В	1.20	1.40	1.30		
С	2.30	2.50	2.40		
D	0.89	1.03	0.915		
F	0.45	0.60	0.535		
G	1.78	2.05	1.83		
Н	2.80	3.00	2.90		
J	0.013	0.10	0.05		
K	0.890	1.00	0.975		
K1	0.903	1.10	1.025		
L	0.45	0.61	0.55		
L1	0.25	0.55	0.40		
M	0.085	0.150	0.110		
а	8°				
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
Z	2.9		
Х	0.8		
Υ	0.9		
С	2.0		
E	1.35		



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